# 2SK0198 (2SK198)

## Silicon N-channel junction FET

#### For low-frequency amplification

#### ■ Features

- High mutual conductance g<sub>m</sub>
- Low-noise characteristics
- Mini type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-sourse voltage	$V_{DS}$	30	V	
Drain-gate voltage (Source open)	$V_{\rm DGO}$	30	V	
Drain current	$I_D$	20	mA	
Gate current	$I_G$	10	mA	
Power dissipation	$P_{\mathrm{D}}$	150	mW	
Channel temperature	T <sub>ch</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

#### Package

- Code
  - Mini3-G1
- Pin Name
  - 1: Source
  - 2: Drain
  - 3: Gate

### ■ Marking Symbol: 10

### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source current *	$I_{DSS}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	0.5	0,	12	mA
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = -30 \text{ V}, V_{DS} = 0$		0	100	nA
Gate-source cutoff voltage	$V_{GSC}$	$V_{DS} = 10 \text{ V}, I_D = 10 \mu\text{A}$	0.1		1.5	V
Forward transfer admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 0.5 \text{ mA}, f = 1 \text{ kHz}$	4			mS
		$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ kHz}$	4			
Short-circuit forward transfer capacitance (Common source)	C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		14		pF
Reverse transfer capacitance (Common source)	C <sub>rss</sub>	28 110 :		3.5		pF
Noise voltage	NV	$V_{DS} = 30 \text{ V}, I_D = 1 \text{ mA}, G_V = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega, \text{Function} = \text{FLAT}$		60		mV

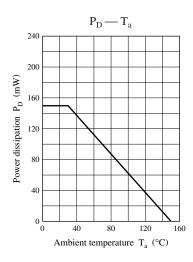
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

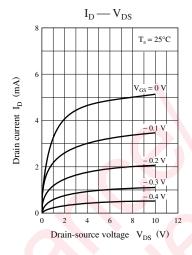
#### 2. \*: Rank classification

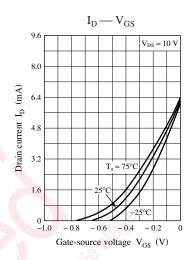
Rank	Р	P Q F	
I <sub>DSS</sub> (mA)	0.5 to 3.0	2.0 to 6.0	4.0 to 12.0

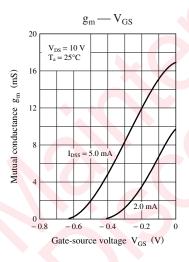
Note) The part number in the parenthesis shows conventional part number.

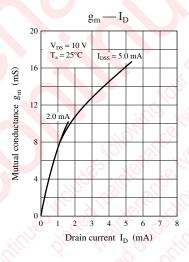
## **Panasonic**

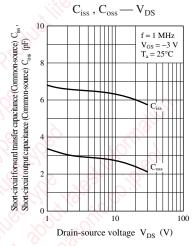


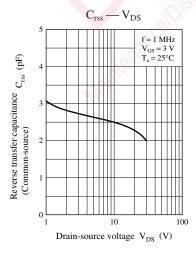


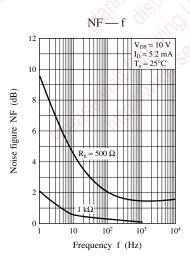






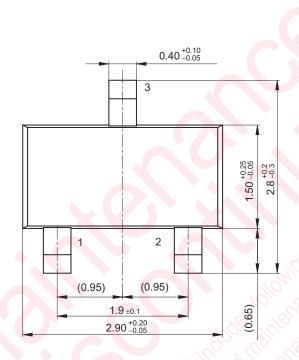


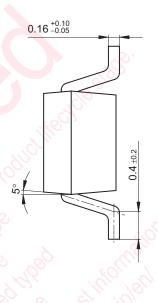


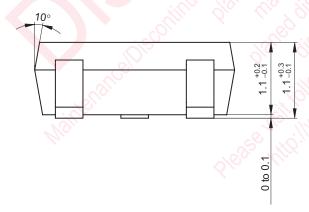


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Mini3-G1 Unit: mm







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